ELECTRONIC MATERIALS
CMP TECHNOLOGIES

ACE NANOCHEM

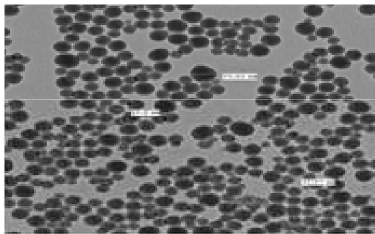
ACESOL® - series
Colloidal Silica
CMP Slurry

ACESOL® BP40 (Wafer Back Side Polishing Slurry)

DESCRIPTION

Acesol® slurries offer a complete solution for your polishing requirements based on the latest colloidal silica technology showing exceptional stability and high manufacturing reproducibility

TEM Image



Precisely Controlled ACESOL® Particles.

KEY FEATURES

- Non-agglomerating slurries with tight Particle distributions
- Enables high removal rates
- Low solid contents, excellent uniformity, no defect
- Products development for customized applications
- Individual, non-setting spherical particles

SPECIFICATION

Abrasive	Colloidal Silica
Mean Particle	40 nm
Specific Gravity (20℃) g/cc	1.105
Solid Content (wt%)	17.5
Viscosity (25℃)	<5
pH (20℃)	11.30
Shelf life	1 Year

Typical Process Results

R/R(aver.Å)	Competitor	1㎛/min
	BP40	1㎛/min

Tool set-up

Polishing Condition

Polisher : Accretech PG300RM
Pressure : 3V (Setting of PG 300RM)
Mixing rate : 20:1 (DI water: Slurry)
Polishing time : 120sec
Slurry Flow Rate : 500 ml/min
Wafer target thickness : < 4mm (8”-12” Wafer)